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# 7/A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Robert M. Japp et al.

Serial No.: 09/625,135 ✓

Art Unit: 3729

Filed: July 25, 2000

Examiner: Smith, S.

For: Composite Laminate Circuit  
Structure and Methods of  
Fabricating

Atty Docket: END919990082US1

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**RESPONSE TO OFFICE ACTION UNDER 37 CFR 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is in response to the Office Action dated November 7, 2001.

In the claims:

Please amend the claims as follows:

*Sub B1*

8.(Amended) A method for fabricating a laminate circuit structure assembly which comprises: providing at least two modularized circuitized voltage plane subassemblies wherein each of the subassemblies comprise at least two signal planes having an external and internal surface disposed about an internal voltage plane; providing dielectric between the signal and voltage planes; and providing dielectric on each external surface of each signal plane; and providing a non-cured or partially cured curable dielectric composition between the subassemblies wherein the dielectric composition comprises, (the same dielectric used in said subassemblies), aligning the subassemblies, and then laminating to cause bonding of the subassemblies.